RJ45MP R1D 3.3E4N RL

Weidmüller Interface GmbH & Co. KG
Klingenbergstraße 26
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Germany

www.weidmueller.com

RJ45 transmitter sockets (magnetics) for gigabit applications (1000 base-T) with integrated compensation actively counteracts inductive and capacitive couplings and saves space on the PCB.

The product range encompasses the following designs:
• 90°, lying (horizontal) and 180°, standing (vertical)
• latch up / latch down
• THT, THR or SMD soldering processes
• Wide range of different design types, also with integrated LEDs and shield contact tabs
• Transmission rates of up to 1 Gbps
• Packed either in a tray (TY) or on a roll (tape-on-reel, RL)
• Compatible with modular RJ45 connector according to ANSI / TIA-1096-A and IEC 60603
• Dielectric strength ≥1500 V AC RMS (2250 V AC peak value) according to IEEE 802.3
• Dielectric strength ≥1500 V AC (peak value) or ≥1500 V DC according to IEC 60603
• Compliance with IEEE 802.3 requirements (1000Base-T, 1 Gbps, IEEE 802.3ab or 100Base-Tx, 100 Mbps, IEEE 802.3u)

Properties and advantages:
• Extended temperature range of –40 °C to +85 °C for maximum performance
• Reinforced gold layer (30µ") for improved corrosion protection
• At least 0.3mm stand-off ensures a perfect soldering result

General ordering data

Version	PCB plug-in connector, RJ45 jacks transformer, 100 MBit/s, POE , THT/THR solder connection, 90°, Latch option: bottom, Number of poles: 10, Tape
Order No.	2661710000
Type	RJ45MP R1D 3.3E4N RL
GTIN (EAN)	4050118675177
Qty.	200 pc(s).
Packaging	Tape

Creation date April 16, 2021 7:38:04 AM CEST

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Technical data

Dimensions and weights

Net weight	10.61 g

System specifications

Latch option	bottom	Mounting onto the PCB	THT/THR solder connection
Number of poles	10	Outgoing elbow	90°
Performance-Category	100 MBit/s, POE	Pitch in inches (P)	0.05 inch
Pitch in mm (P)	1.27 mm	Product family	OMNIMATE Data - RJ45 transformer jack
Protection degree	IP20	Soldering process	Reflow soldering, Manual soldering, Wave soldering
Transmission rate	100 MBit/s, POE		

Electrical properties

Dielectric strength, contact / contact	1000 V DC	Dielectric strength, contact / shield	1500 V DC

Packing

Packaging	Tape	VPE length	345 mm
VPE width	125 mm	VPE height	345 mm

Classifications

ETIM 6.0	EC002637	ETIM 7.0	EC002637
ECLASS 9.0	27-44-04-02	ECLASS 9.1	27-44-04-02
ECLASS 10.0	27-44-04-02	ECLASS 11.0	27-46-02-01

Approvals

ROHS	Conform

Downloads

Engineering Data	STEP
Brochure/Catalogue	Catalogues in PDF-format

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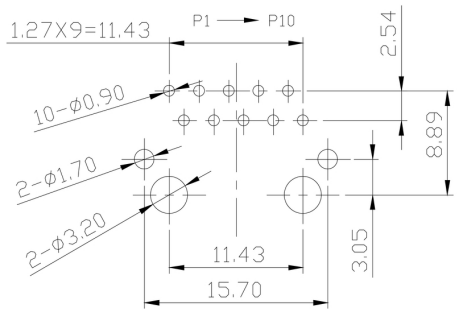
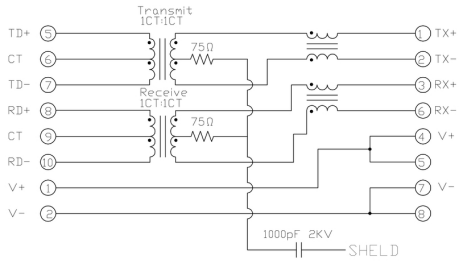
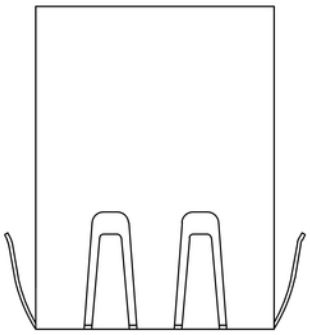
Drawings

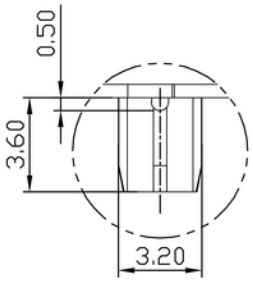
PCB design

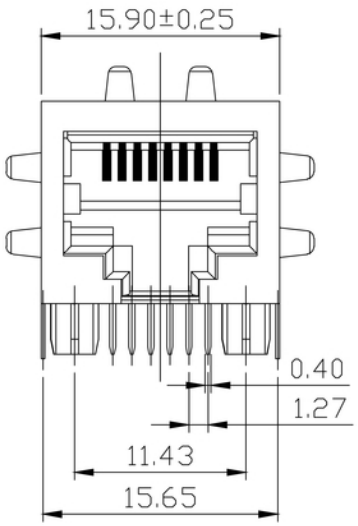


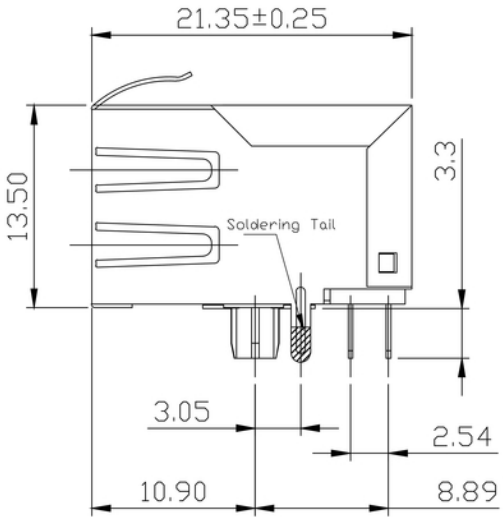


100 Mbit/s & PoE









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Drawings

Characteristics

Inductance	350 µH min. @ 100 kHz, 100 mV, 8 mA DC Bias
Leakage Inductance	0.3 µH max. @ 100 kHz,100 mV
Insertion Loss	1.1 dB max. @ (1 - 100) MHz
Return Loss	18 dB min. @ (1 - 30) MHz 16 dB min. @ (30 - 60) MHz 12 dB min. @ (60 - 80) MHz
Cross Talk	30 dB min. @ (1 - 100) MHz
Common Mode Rejection	30 dB min. @ (1 - 100) MHz

RJ45 G1 R 1 U 3.2 E 4 GY/GY TY RJ45G1 R1U 3.2E4GY/GY TY

Packaging	**TY**	**T**ray in box (manual assembly)
	RL	Tape on **R**eel (automated assembly)
LED	**Y/G**	**Y**ellow/**G**reen
	G/Y	**G**reen/**Y**ellow (standard)
	GY/GY	**G**reen-**Y**ellow/**G**reen-**Y**ellow
	O/G	**O**range/**G**reen
	R/O	**R**ed/**O**range
	...	... (further combinations possible)
	N	without LED
Contact surface thickness	**4**	1 = 3µ", 2 = 6µ", 3 = 15µ", **4 = 30µ"**, 5 = 50µ"
EMI tabs (ground fingers)	**E**	**E** = with EMI tabs
	N	**N** = without EMI tabs
Solder Pin length	**3.2**	3.2 mm
	1.6	1.6 mm
	D	SM**D**
Direction, latch style	**U**	Horizontal (90°, side entry), latch **u**p
	D	Horizontal (90°, side entry), latch **d**own
	V	**V**ertical (180°, top entry)
	Y	Diagonal (45°), latch up
Number of Ports	**1**	1 Port
	12; 14; ...	multi ports side by side, Multiport
	21; 41; ...	multi ports about each other, Multilevel
Assembly on PCB	**R**	Through Hole **R**eflow - TH**R** Soldering process: Wave or **R**eflow soldering
	S	**S**urface Mount Technology - **SMT** Soldering process: Reflow soldering
	T	Through Hole Technology - TH**T** Soldering process: Wave
Performance Category	**C5**	**C**ategory **5**
	C6	**C**ategory **6**
	C6A	**C**ategory **6A**
	C5e	**C**ategory **5e**
	M	10/100 Mbit
	G1	10/100/1000 Mbit
	G10	10 Gbit
	U	**U**nshielded
	MP	10/100 Mbit with **P**OE
	MP+	10/100 Mbit with **P**OE+

Type codes

Wave Solder Profile

Recommended wave solderding profiles

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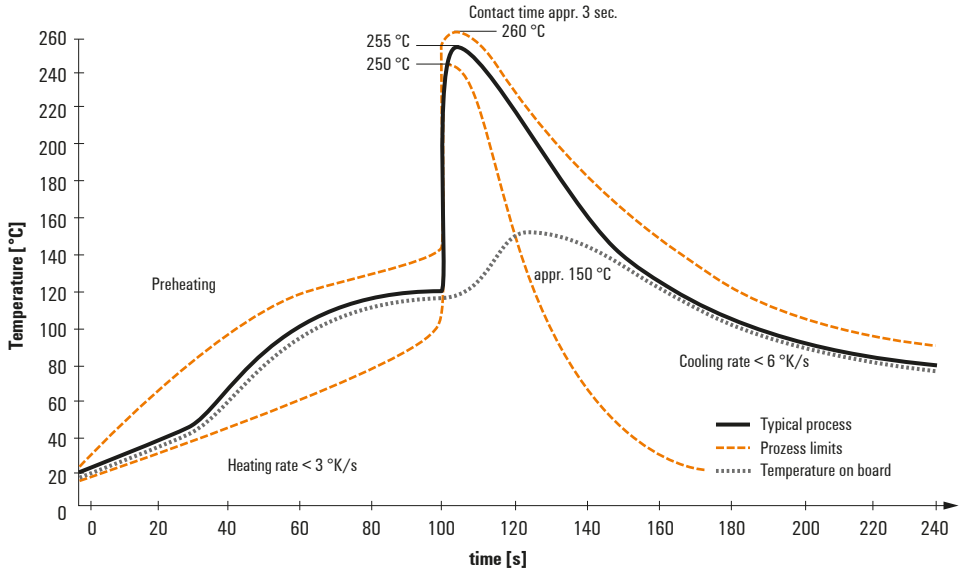
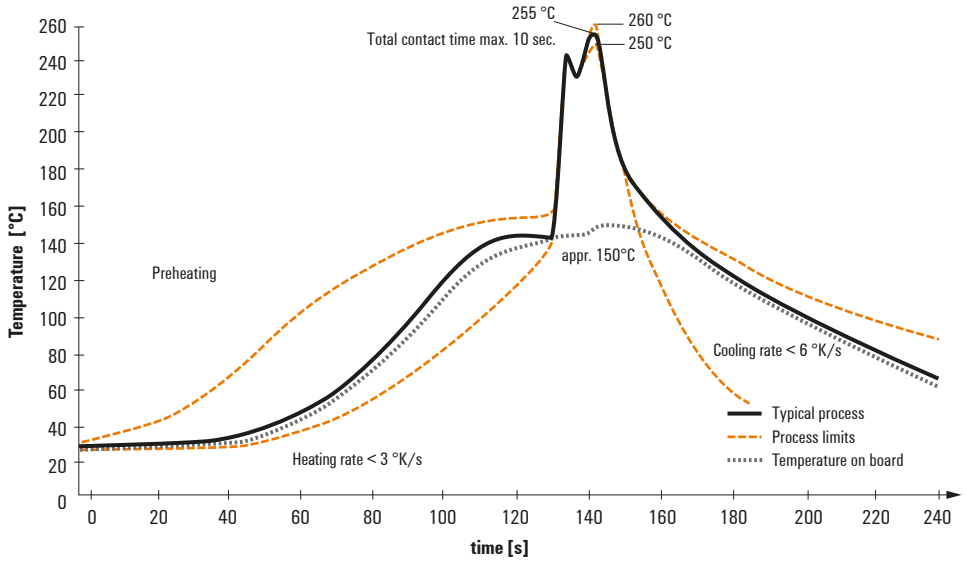
Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:
- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

Reflow Solder Profile

Recommended reflow soldering profile

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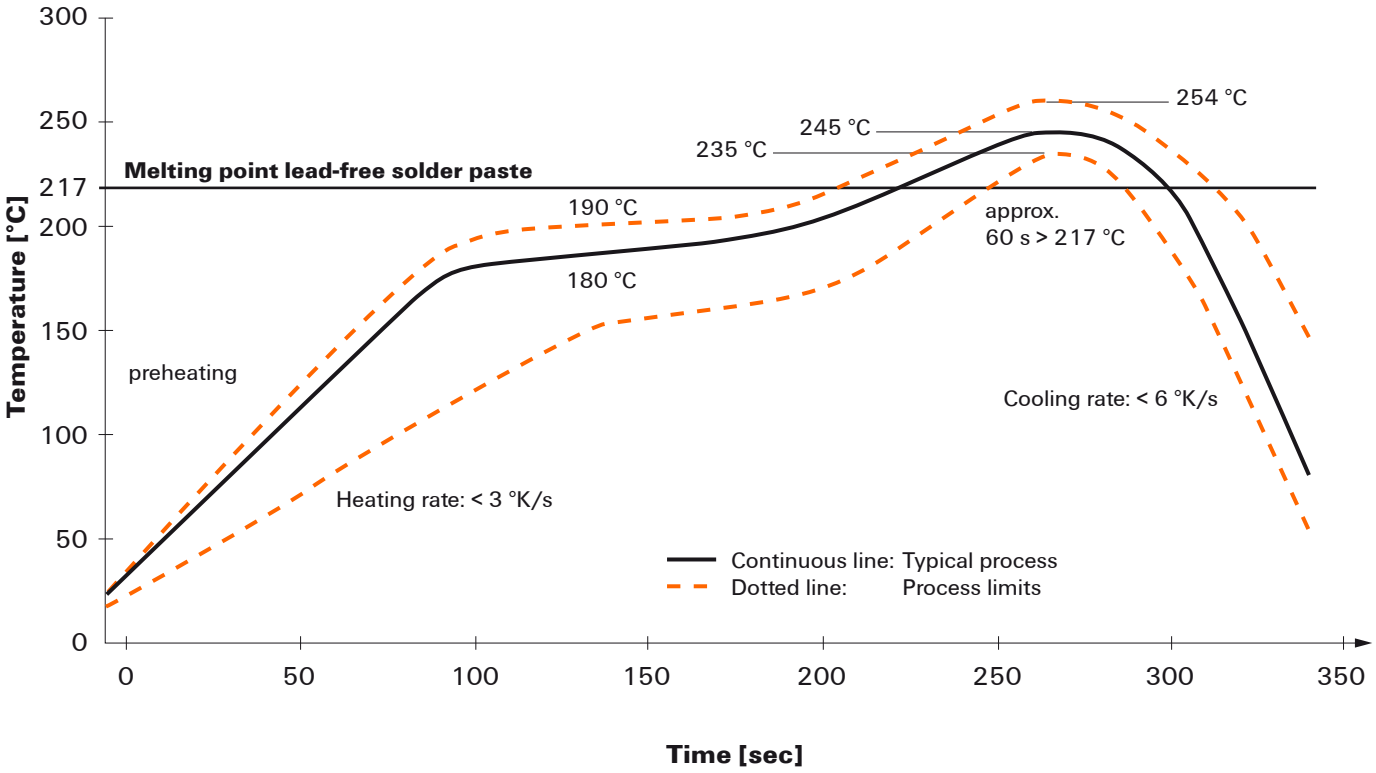

Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:
- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically ≤ +3K/s. In parallel the solder paste is ‚activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at ≥ -6K/s solder is cured. Board and components cool down while avoiding cold cracks.